TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS)

# 2SK3084

# Chopper Regulator DC-DC Converter, and Motor Drive Applications

• 4 V gate drive

 $\begin{array}{ll} \bullet & Low \ drain-source \ ON \ resistance & : R_{DS} \ (ON) = 40 \ m\Omega \ (typ.) \\ \bullet & High \ forward \ transfer \ admittance & : |Y_{fs}| = 27 \ S \ (typ.) \\ \bullet & Low \ leakage \ current & : I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 100 \ V) \\ \bullet & Enhancement-mode & : V_{th} = 0.8 \\ \sim 2.0 \ V \ (V_{DS} = 10 \ V, \ I_{D} = 1 \ mA) \\ \end{array}$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	100	V	
Drain-gate voltage (Ro	<sub>GS</sub> = 20 kΩ)	$V_{DGR}$	100	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
DCDrain current	DC (Note 1)	I <sub>D</sub>	30	Α	
	Pulse (Note 1)	I <sub>DP</sub>	120	Α	
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	65	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	293	mJ	
Avalanche current		I <sub>AR</sub>	30	Α	
Repetitive avalanche e	energy (Note 3)	E <sub>AR</sub>	6.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.92	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	83.3	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

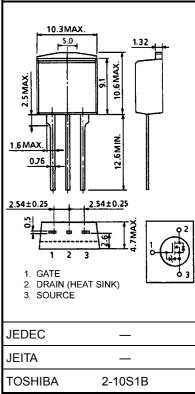
Note 2:  $V_{DD}$  = 25 V,  $T_{ch}$  = 25°C (initial), L = 525  $\mu$ H,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 30 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

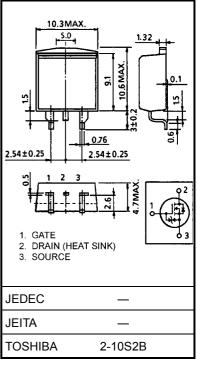
This transistor is an electrostatic sensitive device.

Please handle with caution.





Weight: 1.5 g (typ.)



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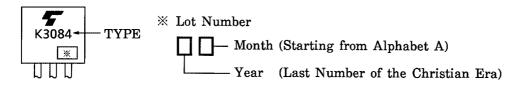
### **Electrical Characteristics (Ta = 25°C)**

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±20	μΑ	
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	_	_	100	μA	
Drain-source br	eakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	100	_	_	V	
Gate threshold v	oltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.8	_	2.0	V	
Drain-source ON resistance		R <sub>DS</sub> (ON)	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 15 A	_	46	70	mΩ	
			V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A	_	40	46		
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 15 A	13	27	_	S	
Input capacitano	e	C <sub>iss</sub>			3250	_	pF	
Reverse transfe	r capacitance	ance C <sub>rss</sub> V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		-	230	_		
Output capacitance		Coss		-	520	_		
Switching time	Rise time	tr	$V_{GS}^{10V}$ $V_{GS}^{10V}$ $R_{L}=$ $3.33\Omega$ $V_{DD}=50V$	_	33	_	- ns	
	Turn-on time	t <sub>on</sub>		_	60	_		
	Fall time	t <sub>f</sub>		_	95	_		
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm W} = 10 \mu \rm s$	1	230	_		
Total gate charge (Gate-source plus gate-drain)			_	68	_	nC		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 80 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$		46		_	
Gate-drain ("miller") charge		$Q_{gd}$			22		_	

## Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_		_	30	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_		_	120	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 30 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 30 A, V <sub>GS</sub> = 0 V	_	140	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dl <sub>DR</sub> / dt = 50 A / μs	-	370	_	nC

### Marking



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